



- 1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]  
FR4/G10 or equivalent high temp material;  
Non-clad
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish-  
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- 3 Solder Balls: Sn63Pb37

**Description:** Giga-snaP BGA SMT Foot  
436 position terminal pins (0.8mm centers, 20x20 array) to SMT solder balls (BGA type). Pin assignment 1:1.

**Tolerances:** diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

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	<p>Drawing: A. Evans</p>	<p>Date: 05/28/09</p>	
	<p>File: SF-BGA436B-B-61 Dwg.mcd</p>	<p>Modified: 09/03/14</p>	